COMPTEST
Services LLC

EXHIBIT 13 APPENDIX C: T-COIL DATA PLOT

CELL BC-10

Test Laboratory: COMPTEST/KYOCERA   Date: 04/13/2012

FCC_C5155_TCoil_CELL_Closed_Ch.476 z (axial)
Communication System: CDMA_Tri_BC0&10, Frequency: 817.9 MHz, Duty Cycle: 1:1
Medium: T-Coil,Medium parameters used: σ = 0 mho/m, ε_r = 1; ρ = 0 kg/m^3
Phantom: HAC Test Arch with AMCC,Phantom section: TCoil Section
DASY4 Configuration:
Probe: AM1DV2 - 1045, , Calibrated: 9/15/2011
Sensor-Surface: 0mm (Fix Surface),
Electronics: DAE4 Sn527,Calibrated: 7/13/2011
Measurement SW: DASY4, V4.7 Build 80
Postprocessing SW: SEMCAD, V1.8 Build 186
Temperature:
Room T = 21.8   1 deg C, Liquid T = 22.0   1 deg C

General Scans_476/z (axial) 4.2mm 50 x 50/ABM Interpolated SNR(x,y,z) (121x121x1):
Measurement grid: dx=10mm, dy=10mm
Signal Type: Audio File (.wav) 48k_voice_1kHz_1s.wav
BWC applied: 0.155979 dB
Device Reference Point: 0.000, 0.000, -6.30 mm
Cursor:
ABM1/ABM2 = 52.0 dB
ABM1 comp = -0.980 dB A/m
BWC Factor = 0.155979 dB
Location: 0.4, -0.4, 3.7 mm

General Scans_476/z (axial) fine 2mm 8 x 8/ABM Interpolated SNR(x,y,z) (41x41x1):
Measurement grid: dx=10mm, dy=10mm
Signal Type: Audio File (.wav) 48k_voice_1kHz_1s.wav
BWC applied: 0.155979 dB
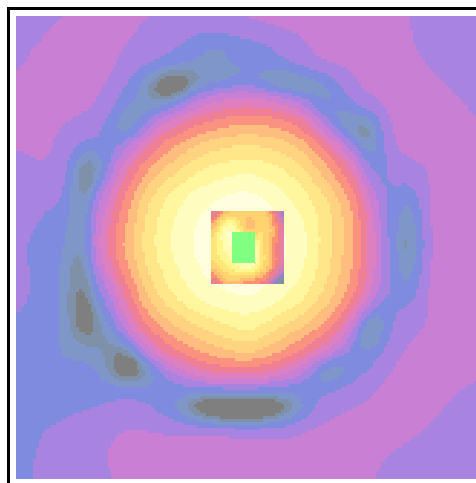Device Reference Point: 0.000, 0.000, -6.30 mm
Cursor:
ABM1/ABM2 = 52.0 dB
ABM1 comp = -0.870 dB A/m
BWC Factor = 0.155979 dB
Location: 0.4, 0.4, 3.7 mm

0 dB = 398.7

Test Laboratory: COMPTEST/KYOCERA   Date: 04/13/2012

FCC_ C5155_TCoil_CELL_ Closed_Ch.476 x (longitudinal)
Communication System: CDMA_Tri_BC0&10, Frequency: 817.9 MHz, Duty Cycle: 1:1
Medium: T-Coil,Medium parameters used: σ = 0 mho/m, ε_r = 1; ρ = 0 kg/m^3
Phantom: HAC Test Arch with AMCC,Phantom section: TCoil Section
DASY4 Configuration:
Probe: AM1DV2 - 1045, , Calibrated: 9/15/2011
Sensor-Surface: 0mm (Fix Surface),
Electronics: DAE4 Sn527,Calibrated: 7/13/2011
Measurement SW: DASY4, V4.7 Build 80
Postprocessing SW: SEMCAD, V1.8 Build 186
Temperature:
Room T = 21.8   1 deg C, Liquid T = 22.0   1 deg C

General Scans_476/x (longitudinal) 4.2mm 50 x 50/ABM Interpolated SNR(x,y,z) (121x121x1):
Measurement grid: dx=10mm, dy=10mm
Signal Type: Audio File (.wav) 48k_voice_1kHz_1s.wav
BWC applied: 0.155979 dB
Device Reference Point: 0.000, 0.000, -6.30 mm
Cursor:
ABM1/ABM2 = 48.2 dB
ABM1 comp = -9.26 dB A/m
BWC Factor = 0.155979 dB
Location: -5.8, -0.4, 3.7 mm

General Scans_476/x (longitudinal) fine 2mm 8 x 8/ABM Interpolated SNR(x,y,z) (41x41x1):
Measurement grid: dx=10mm, dy=10mm
Signal Type: Audio File (.wav) 48k_voice_1kHz_1s.wav
BWC applied: 0.155979 dB
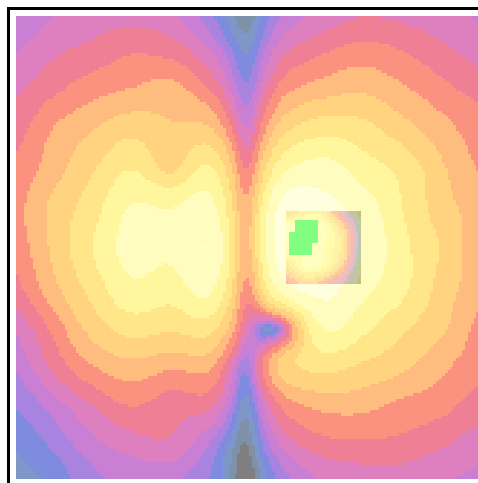Device Reference Point: 0.000, 0.000, -6.30 mm
Cursor:
ABM1/ABM2 = 47.7 dB
ABM1 comp = -9.77 dB A/m
BWC Factor = 0.155979 dB
Location: -6.3, -1.8, 3.7 mm

0 dB = 256.4

Test Laboratory: COMPTEST/KYOCERA　　　　　　　　　　　　　　　　Date: 04/13/2012

FCC_ C5155_TCoil_CELL_ Closed_Ch. 476 y (transversal)
Communication System: CDMA_Tri_BC0&10, Frequency: 817.9 MHz, Duty Cycle: 1:1
Medium: T-Coil,Medium parameters used: σ = 0 mho/m, ε_r = 1; ρ = 0 kg/m^3
Phantom: HAC Test Arch with AMCC,Phantom section: TCoil Section
DASY4 Configuration:
Probe: AM1DV2 - 1045, , Calibrated: 9/15/2011
Sensor-Surface: 0mm (Fix Surface),
Electronics: DAE4 Sn527,Calibrated: 7/13/2011
Measurement SW: DASY4, V4.7 Build 80
Postprocessing SW: SEMCAD, V1.8 Build 186
Temperature:
Room T = 21.8　　　　1 deg C, Liquid T = 22.0　　　　1 deg C

General Scans_476/y (transversal) 4.2mm 50 x 50/ABM Interpolated SNR(x,y,z) (121x121x1):
Measurement grid: dx=10mm, dy=10mm
Signal Type: Audio File (.wav) 48k_voice_1kHz_1s.wav
BWC applied: 0.155979 dB
Device Reference Point: 0.000, 0.000, -6.30 mm
Cursor:
ABM1/ABM2 = 47.7 dB
ABM1 comp = -9.60 dB A/m
BWC Factor = 0.155979 dB
Location: 0.4, 7.1, 3.7 mm

General Scans_476/y (transversal) fine 2mm 8 x 8/ABM Interpolated SNR(x,y,z) (41x41x1):
Measurement grid: dx=10mm, dy=10mm
Signal Type: Audio File (.wav) 48k_voice_1kHz_1s.wav
BWC applied: 0.155979 dB
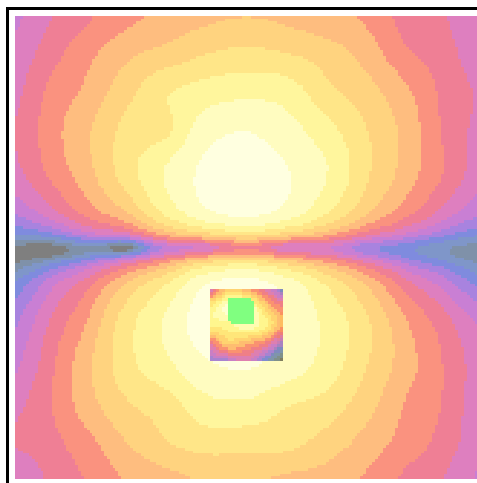Device Reference Point: 0.000, 0.000, -6.30 mm
Cursor:
ABM1/ABM2 = 48.1 dB
ABM1 comp = -9.19 dB A/m
BWC Factor = 0.155979 dB
Location: 0.8, 6.7, 3.7 mm

0 dB = 243.2

Test Laboratory: COMPTEST/KYOCERA   Date: 04/13/2012

FCC_C5155_TCoil_CELL_Closed_Ch.580 z (axial)
Communication System: CDMA_Tri_BC0&10, Frequency: 820.5 MHz, Duty Cycle: 1:1
Medium: T-Coil,Medium parameters used: σ = 0 mho/m, ε_r = 1; ρ = 0 kg/m^3
Phantom: HAC Test Arch with AMCC,Phantom section: TCoil Section
DASY4 Configuration:
Probe: AM1DV2 - 1045, , Calibrated: 9/15/2011
Sensor-Surface: 0mm (Fix Surface),
Electronics: DAE4 Sn527,Calibrated: 7/13/2011
Measurement SW: DASY4, V4.7 Build 80
Postprocessing SW: SEMCAD, V1.8 Build 186
Temperature:
Room T = 21.8   1 deg C, Liquid T = 22.0   1 deg C

General Scans_580/z (axial) 4.2mm 50 x 50/ABM Interpolated SNR(x,y,z) (121x121x1):
Measurement grid: dx=10mm, dy=10mm
Signal Type: Audio File (.wav) 48k_voice_1kHz_1s.wav
BWC applied: 0.155979 dB
Device Reference Point: 0.000, 0.000, -6.30 mm
Cursor:
ABM1/ABM2 = 52.2 dB
ABM1 comp = -1.41 dB A/m
BWC Factor = 0.155979 dB
Location: 0, -2.1, 3.7 mm

General Scans_580/z (axial) fine 2mm 8 x 8/ABM Interpolated SNR(x,y,z) (41x41x1):
Measurement grid: dx=10mm, dy=10mm
Signal Type: Audio File (.wav) 48k_voice_1kHz_1s.wav
BWC applied: 0.155979 dB
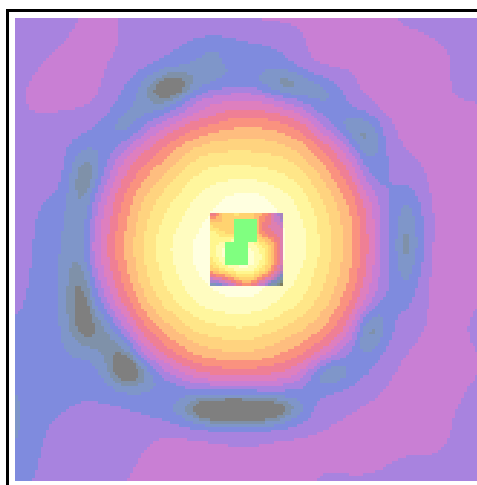Device Reference Point: 0.000, 0.000, -6.30 mm
Cursor:
ABM1/ABM2 = 51.9 dB
ABM1 comp = -1.33 dB A/m
BWC Factor = 0.155979 dB
Location: 1, 0.6, 3.7 mm

0 dB = 406.7

Test Laboratory: COMPTEST/KYOCERA   Date: 04/13/2012

FCC_ C5155_TCoil_CELL_ Closed_Ch. 580 x (longitudinal)
Communication System: CDMA_Tri_BC0&10, Frequency: 820.5 MHz, Duty Cycle: 1:1
Medium: T-Coil,Medium parameters used: $\sigma = 0$ mho/m, $\varepsilon_r = 1$; $\rho = 0$ kg/m^3
Phantom: HAC Test Arch with AMCC,Phantom section: TCoil Section
DASY4 Configuration:
Probe: AM1DV2 - 1045, , Calibrated: 9/15/2011
Sensor-Surface: 0mm (Fix Surface),
Electronics: DAE4 Sn527,Calibrated: 7/13/2011
Measurement SW: DASY4, V4.7 Build 80
Postprocessing SW: SEMCAD, V1.8 Build 186
Temperature:
Room T = 21.8   1 deg C, Liquid T = 22.0   1 deg C

General Scans_580/x (longitudinal) 4.2mm 50 x 50/ABM Interpolated SNR(x,y,z) (121x121x1):
Measurement grid: dx=10mm, dy=10mm
Signal Type: Audio File (.wav) 48k_voice_1kHz_1s.wav
BWC applied: 0.155979 dB
Device Reference Point: 0.000, 0.000, -6.30 mm
Cursor:
ABM1/ABM2 = 48.1 dB
ABM1 comp = -9.67 dB A/m
BWC Factor = 0.155979 dB
Location: -5.8, -0.8, 3.7 mm

General Scans_580/x (longitudinal) fine 2mm 8 x 8/ABM Interpolated SNR(x,y,z) (41x41x1):
Measurement grid: dx=10mm, dy=10mm
Signal Type: Audio File (.wav) 48k_voice_1kHz_1s.wav
BWC applied: 0.155979 dB
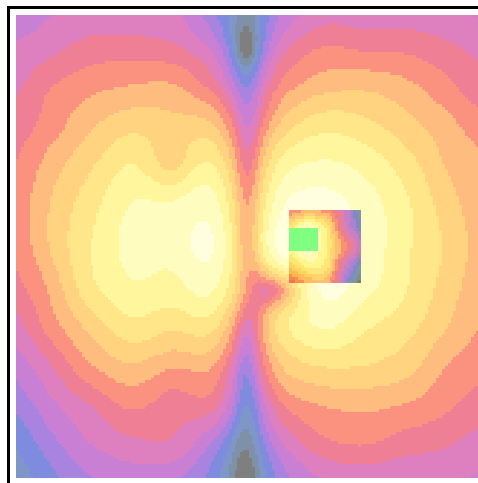Device Reference Point: 0.000, 0.000, -6.30 mm
Cursor:
ABM1/ABM2 = 48.5 dB
ABM1 comp = -9.10 dB A/m
BWC Factor = 0.155979 dB
Location: -6.3, -0.8, 3.7 mm

0 dB = 254.6

Test Laboratory: COMPTEST/KYOCERA

Date: 04/13/2012

FCC_ C5155_TCoil_CELL_ Closed_Ch. 580 y (transversal)
Communication System: CDMA_Tri_BC0&10, Frequency: 820.5 MHz, Duty Cycle: 1:1
Medium: T-Coil,Medium parameters used: σ = 0 mho/m, $ε_r$ = 1; ρ = 0 kg/m^3
Phantom: HAC Test Arch with AMCC,Phantom section: TCoil Section
DASY4 Configuration:
Probe: AM1DV2 - 1045, , Calibrated: 9/15/2011
Sensor-Surface: 0mm (Fix Surface),
Electronics: DAE4 Sn527,Calibrated: 7/13/2011
Measurement SW: DASY4, V4.7 Build 80
Postprocessing SW: SEMCAD, V1.8 Build 186
Temperature:
Room T = 21.8   1 deg C, Liquid T = 22.0   1 deg C

General Scans_580/y (transversal) 4.2mm 50 x 50/ABM Interpolated SNR(x,y,z) (121x121x1):
Measurement grid: dx=10mm, dy=10mm
Signal Type: Audio File (.wav) 48k_voice_1kHz_1s.wav
BWC applied: 0.155979 dB
Device Reference Point: 0.000, 0.000, -6.30 mm
Cursor:
ABM1/ABM2 = 47.9 dB
ABM1 comp = -9.82 dB A/m
BWC Factor = 0.155979 dB
Location: 0.4, 7.9, 3.7 mm

General Scans_580/y (transversal) fine 2mm 8 x 8/ABM Interpolated SNR(x,y,z) (41x41x1):
Measurement grid: dx=10mm, dy=10mm
Signal Type: Audio File (.wav) 48k_voice_1kHz_1s.wav
BWC applied: 0.155979 dB
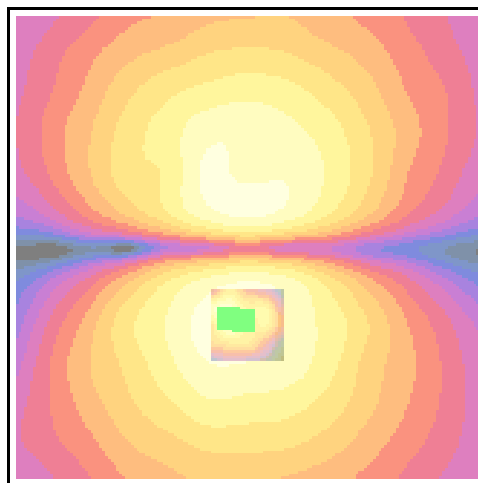Device Reference Point: 0.000, 0.000, -6.30 mm
Cursor:
ABM1/ABM2 = 47.4 dB
ABM1 comp = -9.82 dB A/m
BWC Factor = 0.155979 dB
Location: 2, 7.5, 3.7 mm

0 dB = 247.0

Test Laboratory: COMPTEST/KYOCERA   Date: 04/13/2012

FCC_C5155_TCoil_CELL_Closed_Ch.684 z (axial)
Communication System: CDMA_Tri_BC0&10, Frequency: 823.1 MHz, Duty Cycle: 1:1
Medium: T-Coil,Medium parameters used: $\sigma = 0$ mho/m, $\varepsilon_r = 1$; $\rho = 0$ kg/m^3
Phantom: HAC Test Arch with AMCC,Phantom section: TCoil Section
DASY4 Configuration:
Probe: AM1DV2 - 1045, , Calibrated: 9/15/2011
Sensor-Surface: 0mm (Fix Surface),
Electronics: DAE4 Sn527,Calibrated: 7/13/2011
Measurement SW: DASY4, V4.7 Build 80
Postprocessing SW: SEMCAD, V1.8 Build 186
Temperature:
Room T = 21.8   1 deg C, Liquid T = 22.0   1 deg C

General Scans_684/z (axial) 4.2mm 50 x 50/ABM Interpolated SNR(x,y,z) (121x121x1):
Measurement grid: dx=10mm, dy=10mm
Signal Type: Audio File (.wav) 48k_voice_1kHz_1s.wav
BWC applied: 0.155979 dB
Device Reference Point: 0.000, 0.000, -6.30 mm
Cursor:
ABM1/ABM2 = 52.4 dB
ABM1 comp = -0.721 dB A/m
BWC Factor = 0.155979 dB
Location: 0.4, -0.4, 3.7 mm

General Scans_684/z (axial) fine 2mm 8 x 8/ABM Interpolated SNR(x,y,z) (41x41x1):
Measurement grid: dx=10mm, dy=10mm
Signal Type: Audio File (.wav) 48k_voice_1kHz_1s.wav
BWC applied: 0.155979 dB
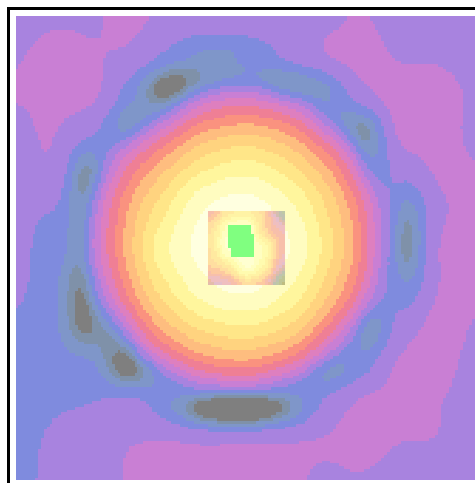Device Reference Point: 0.000, 0.000, -6.30 mm
Cursor:
ABM1/ABM2 = 52.4 dB
ABM1 comp = -0.810 dB A/m
BWC Factor = 0.155979 dB
Location: 0.8, -1.2, 3.7 mm

0 dB = 417.3

Test Laboratory: COMPTEST/KYOCERA   Date: 04/13/2012

FCC_ C5155_TCoil_CELL_ Closed_Ch. 684 x (longitudinal)
Communication System: CDMA_Tri_BC0&10, Frequency: 823.1 MHz, Duty Cycle: 1:1
Medium: T-Coil,Medium parameters used: σ = 0 mho/m, $ε_r$ = 1; ρ = 0 kg/m^3
Phantom: HAC Test Arch with AMCC,Phantom section: TCoil Section
DASY4 Configuration:
Probe: AM1DV2 - 1045, , Calibrated: 9/15/2011
Sensor-Surface: 0mm (Fix Surface),
Electronics: DAE4 Sn527,Calibrated: 7/13/2011
Measurement SW: DASY4, V4.7 Build 80
Postprocessing SW: SEMCAD, V1.8 Build 186
Temperature:
Room T = 21.8   1 deg C, Liquid T = 22.0   1 deg C

General Scans_684/x (longitudinal) 4.2mm 50 x 50/ABM Interpolated SNR(x,y,z) (121x121x1):
Measurement grid: dx=10mm, dy=10mm
Signal Type: Audio File (.wav) 48k_voice_1kHz_1s.wav
BWC applied: 0.155979 dB
Device Reference Point: 0.000, 0.000, -6.30 mm
Cursor:
ABM1/ABM2 = 47.8 dB
ABM1 comp = -9.91 dB A/m
BWC Factor = 0.155979 dB
Location: -7.9, -0.4, 3.7 mm

General Scans_684/x (longitudinal) fine 2mm 8 x 8/ABM Interpolated SNR(x,y,z) (41x41x1):
Measurement grid: dx=10mm, dy=10mm
Signal Type: Audio File (.wav) 48k_voice_1kHz_1s.wav
BWC applied: 0.155979 dB
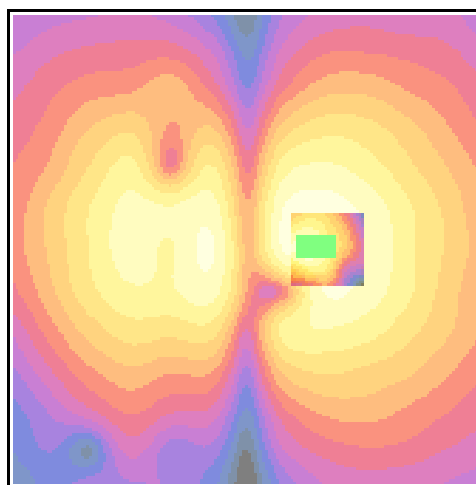Device Reference Point: 0.000, 0.000, -6.30 mm
Cursor:
ABM1/ABM2 = 48.4 dB
ABM1 comp = -9.23 dB A/m
BWC Factor = 0.155979 dB
Location: -6.1, -0.2, 3.7 mm

0 dB = 245.3

Test Laboratory: COMPTEST/KYOCERA   Date: 04/13/2012

FCC_ C5155_TCoil_CELL_Closed_Ch. 684 y (transversal)
Communication System: CDMA_Tri_BC0&10, Frequency: 823.1 MHz, Duty Cycle: 1:1
Medium: T-Coil,Medium parameters used: σ = 0 mho/m, $ε_r$ = 1; ρ = 0 kg/m^3
Phantom: HAC Test Arch with AMCC,Phantom section: TCoil Section
DASY4 Configuration:
Probe: AM1DV2 - 1045, , Calibrated: 9/15/2011
Sensor-Surface: 0mm (Fix Surface),
Electronics: DAE4 Sn527,Calibrated: 7/13/2011
Measurement SW: DASY4, V4.7 Build 80
Postprocessing SW: SEMCAD, V1.8 Build 186
Temperature:
Room T = 21.8   1 deg C, Liquid T = 22.0   1 deg C

General Scans_684/y (transversal) 4.2mm 50 x 50/ABM Interpolated SNR(x,y,z) (121x121x1):
Measurement grid: dx=10mm, dy=10mm
Signal Type: Audio File (.wav) 48k_voice_1kHz_1s.wav
BWC applied: 0.155979 dB
Device Reference Point: 0.000, 0.000, -6.30 mm
Cursor:
ABM1/ABM2 = 47.9 dB
ABM1 comp = -9.68 dB A/m
BWC Factor = 0.155979 dB
Location: 0.8, 7.9, 3.7 mm

General Scans_684/y (transversal) fine 2mm 8 x 8/ABM Interpolated SNR(x,y,z) (41x41x1):
Measurement grid: dx=10mm, dy=10mm
Signal Type: Audio File (.wav) 48k_voice_1kHz_1s.wav
BWC applied: 0.155979 dB
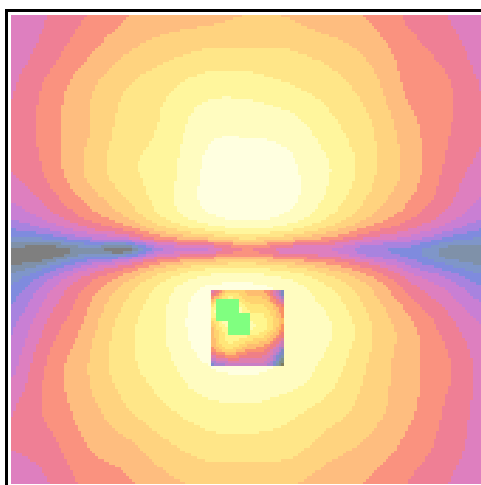Device Reference Point: 0.000, 0.000, -6.30 mm
Cursor:
ABM1/ABM2 = 48.2 dB
ABM1 comp = -8.97 dB A/m
BWC Factor = 0.155979 dB
Location: 2, 6.5, 3.7 mm

0 dB = 248.2

CELL-BC0

Test Laboratory: COMPTEST/KYOCERA   Date: 04/13/2012

FCC_C5155_TCoil_CELL_Closed_Ch.1013 z (axial)
Communication System: CDMA_Tri_BC0&10, Frequency: 824.7 MHz, Duty Cycle: 1:1
Medium: T-Coil,Medium parameters used: $\sigma = 0$ mho/m, $\varepsilon_r = 1$; $\rho = 0$ kg/m^3
Phantom: HAC Test Arch with AMCC,Phantom section: TCoil Section
DASY4 Configuration:
Probe: AM1DV2 - 1045, , Calibrated: 9/15/2011
Sensor-Surface: 0mm (Fix Surface),
Electronics: DAE4 Sn527,Calibrated: 7/13/2011
Measurement SW: DASY4, V4.7 Build 80
Postprocessing SW: SEMCAD, V1.8 Build 186
Temperature:
Room T = 21.8   1 deg C, Liquid T = 22.0   1 deg C

General Scans_1013/z (axial) fine 2mm 8 x 8/ABM Interpolated SNR(x,y,z) (41x41x1):
Measurement grid: dx=10mm, dy=10mm
Signal Type: Audio File (.wav) 48k_voice_1kHz_1s.wav
BWC applied: 0.155979 dB
Device Reference Point: 0.000, 0.000, -6.30 mm
Cursor:
ABM1/ABM2 = 52.4 dB
ABM1 comp = -0.591 dB A/m
BWC Factor = 0.155979 dB
Location: 0.4, 0, 3.7 mm

General Scans_1013/z (axial) 4.2mm 50 x 50/ABM Interpolated Signal(x,y,z) (121x121x1):
Measurement grid: dx=10mm, dy=10mm
Signal Type: Audio File (.wav) 48k_voice_1kHz_1s.wav
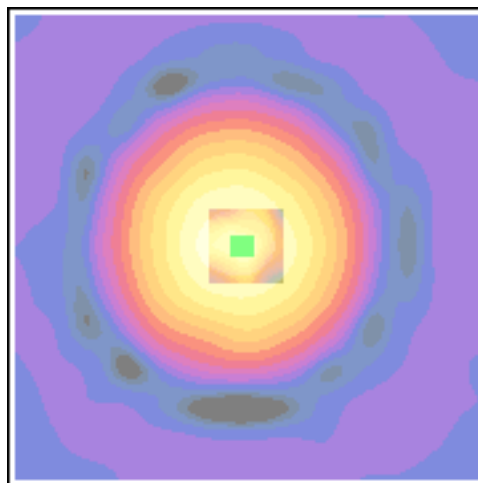BWC applied: 0.155979 dB
Device Reference Point: 0.000, 0.000, -6.30 mm
Cursor:
ABM1 = -0.622 dB A/m
BWC Factor = 0.155979 dB
Location: 0.8, 0, 3.7 mm

0 dB = 419.1

Test Laboratory: COMPTEST/KYOCERA   Date: 04/13/2012

FCC_ C5155_TCoil_CELL_ Closed_Ch. 1013 x (longitudinal)
Communication System: CDMA_Tri_BC0&10, Frequency: 824.7 MHz, Duty Cycle: 1:1
Medium: T-Coil,Medium parameters used: σ = 0 mho/m, ε_r = 1; ρ = 0 kg/m^3
Phantom: HAC Test Arch with AMCC,Phantom section: TCoil Section
DASY4 Configuration:
Probe: AM1DV2 - 1045, , Calibrated: 9/15/2011
Sensor-Surface: 0mm (Fix Surface),
Electronics: DAE4 Sn527,Calibrated: 7/13/2011
Measurement SW: DASY4, V4.7 Build 80
Postprocessing SW: SEMCAD, V1.8 Build 186
Temperature:
Room T = 21.8   1 deg C, Liquid T = 22.0   1 deg C

General Scans_1013/x (longitudinal) 4.2mm 50 x 50/ABM Interpolated SNR(x,y,z) (121x121x1):
Measurement grid: dx=10mm, dy=10mm
Signal Type: Audio File (.wav) 48k_voice_1kHz_1s.wav
BWC applied: 0.155979 dB
Device Reference Point: 0.000, 0.000, -6.30 mm
Cursor:
ABM1/ABM2 = 47.4 dB
ABM1 comp = -10.1 dB A/m
BWC Factor = 0.155979 dB
Location: -6.2, -1.3, 3.7 mm

General Scans_1013/x (longitudinal) fine 2mm 8 x 8/ABM Interpolated SNR(x,y,z) (41x41x1):
Measurement grid: dx=10mm, dy=10mm
Signal Type: Audio File (.wav) 48k_voice_1kHz_1s.wav
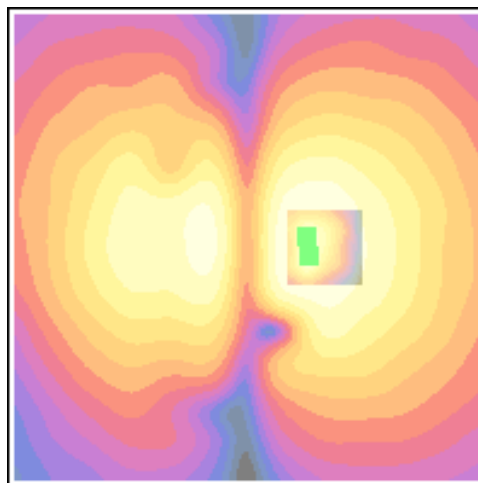BWC applied: 0.155979 dB
Device Reference Point: 0.000, 0.000, -6.30 mm
Cursor:
ABM1/ABM2 = 48.3 dB
ABM1 comp = -9.49 dB A/m
BWC Factor = 0.155979 dB
Location: -6.5, 0.8, 3.7 mm

0 dB = 234.2

Test Laboratory: COMPTEST/KYOCERA   Date: 04/13/2012

FCC_ C5155_TCoil_CELL_ Closed_Ch. 1013 y (transversal)
Communication System: CDMA_Tri_BC0&10, Frequency: 824.7 MHz, Duty Cycle: 1:1
Medium: T-Coil,Medium parameters used: σ = 0 mho/m, ε_r = 1; ρ = 0 kg/m^3
Phantom: HAC Test Arch with AMCC,Phantom section: TCoil Section
DASY4 Configuration:
Probe: AM1DV2 - 1045, , Calibrated: 9/15/2011
Sensor-Surface: 0mm (Fix Surface),
Electronics: DAE4 Sn527,Calibrated: 7/13/2011
Measurement SW: DASY4, V4.7 Build 80
Postprocessing SW: SEMCAD, V1.8 Build 186
Temperature:
Room T = 21.8   1 deg C, Liquid T = 22.0   1 deg C

General Scans_1013/y (transversal) 4.2mm 50 x 50/ABM Interpolated SNR(x,y,z) (121x121x1):
Measurement grid: dx=10mm, dy=10mm
Signal Type: Audio File (.wav) 48k_voice_1kHz_1s.wav
BWC applied: 0.155979 dB
Device Reference Point: 0.000, 0.000, -6.30 mm
Cursor:
ABM1/ABM2 = 48.0 dB
ABM1 comp = -9.54 dB A/m
BWC Factor = 0.155979 dB
Location: 0.4, 7.5, 3.7 mm

General Scans_1013/y (transversal) fine 2mm 8 x 8/ABM Interpolated SNR(x,y,z) (41x41x1):
Measurement grid: dx=10mm, dy=10mm
Signal Type: Audio File (.wav) 48k_voice_1kHz_1s.wav
BWC applied: 0.155979 dB
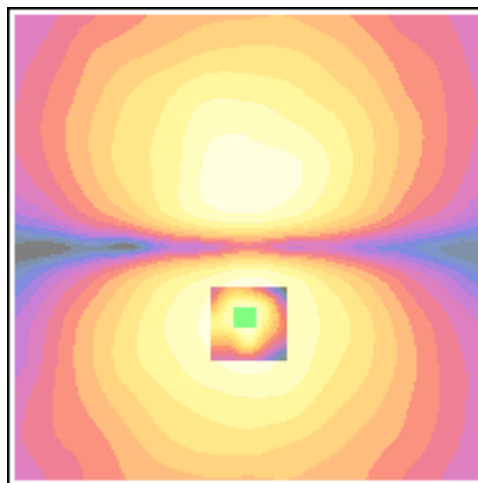Device Reference Point: 0.000, 0.000, -6.30 mm
Cursor:
ABM1/ABM2 = 47.9 dB
ABM1 comp = -9.68 dB A/m
BWC Factor = 0.155979 dB
Location: 0.2, 7.7, 3.7 mm

0 dB = 250.5

Test Laboratory: COMPTEST/KYOCERA   Date: 04/13/2012

FCC_C5120_TCoil_CELL_Closed_Ch.384 z (axial)
Communication System: CDMA_Tri_BC0&10, Frequency: 836.52 MHz, Duty Cycle: 1:1
Medium: T-Coil,Medium parameters used: $\sigma = 0$ mho/m, $\varepsilon_r = 1$; $\rho = 0$ kg/m^3
Phantom: HAC Test Arch with AMCC,Phantom section: TCoil Section
DASY4 Configuration:
Probe: AM1DV2 - 1045, , Calibrated: 9/15/2011
Sensor-Surface: 0mm (Fix Surface),
Electronics: DAE4 Sn527,Calibrated: 7/13/2011
Measurement SW: DASY4, V4.7 Build 80
Postprocessing SW: SEMCAD, V1.8 Build 186
Temperature:
Room T = 21.8   1 deg C, Liquid T = 22.0   1 deg C

General Scans_384/z (axial) 4.2mm 50 x 50/ABM Interpolated SNR(x,y,z) (121x121x1):
Measurement grid: dx=10mm, dy=10mm
Signal Type: Audio File (.wav) 48k_voice_1kHz_1s.wav
BWC applied: 0.155979 dB
Device Reference Point: 0.000, 0.000, -6.30 mm
Cursor:
ABM1/ABM2 = 53.2 dB
ABM1 comp = -0.208 dB A/m
BWC Factor = 0.155979 dB
Location: 0.4, -0.4, 3.7 mm

General Scans_384/z (axial) fine 2mm 8 x 8/ABM Interpolated SNR(x,y,z) (41x41x1):
Measurement grid: dx=10mm, dy=10mm
Signal Type: Audio File (.wav) 48k_voice_1kHz_1s.wav
BWC applied: 0.155979 dB
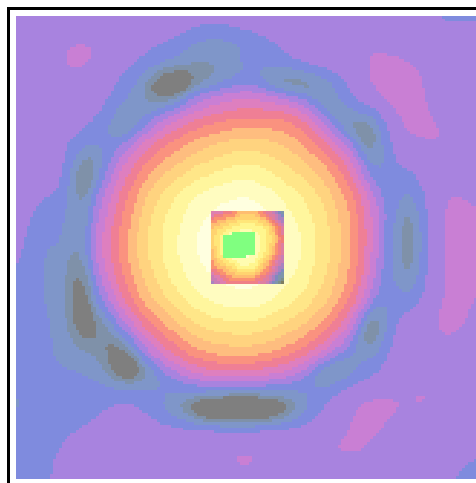Device Reference Point: 0.000, 0.000, -6.30 mm
Cursor:
ABM1/ABM2 = 52.8 dB
ABM1 comp = -0.572 dB A/m
BWC Factor = 0.155979 dB
Location: 1.4, 0, 3.7 mm

0 dB = 457.7

Test Laboratory: COMPTEST/KYOCERA   Date: 04/13/2012

FCC_ C5155_TCoil_CELL_ Closed_Ch.384 x (longitudinal)
Communication System: CDMA_Tri_BC0&10, Frequency: 836.52 MHz, Duty Cycle: 1:1
Medium: T-Coil,Medium parameters used: σ = 0 mho/m, ε_r = 1; ρ = 0 kg/m^3
Phantom: HAC Test Arch with AMCC,Phantom section: TCoil Section
DASY4 Configuration:
Probe: AM1DV2 - 1045, , Calibrated: 9/15/2011
Sensor-Surface: 0mm (Fix Surface),
Electronics: DAE4 Sn527,Calibrated: 7/13/2011
Measurement SW: DASY4, V4.7 Build 80
Postprocessing SW: SEMCAD, V1.8 Build 186
Temperature:
Room T = 21.8   1 deg C, Liquid T = 22.0   1 deg C

General Scans_384/x (longitudinal) 4.2mm 50 x 50/ABM Interpolated SNR(x,y,z) (121x121x1):
Measurement grid: dx=10mm, dy=10mm
Signal Type: Audio File (.wav) 48k_voice_1kHz_1s.wav
BWC applied: 0.155979 dB
Device Reference Point: 0.000, 0.000, -6.30 mm
Cursor:
ABM1/ABM2 = 48.3 dB
ABM1 comp = -9.30 dB A/m
BWC Factor = 0.155979 dB
Location: -6.2, -0.4, 3.7 mm

General Scans_384/x (longitudinal) fine 2mm 8 x 8/ABM Interpolated SNR(x,y,z) (41x41x1):
Measurement grid: dx=10mm, dy=10mm
Signal Type: Audio File (.wav) 48k_voice_1kHz_1s.wav
BWC applied: 0.155979 dB
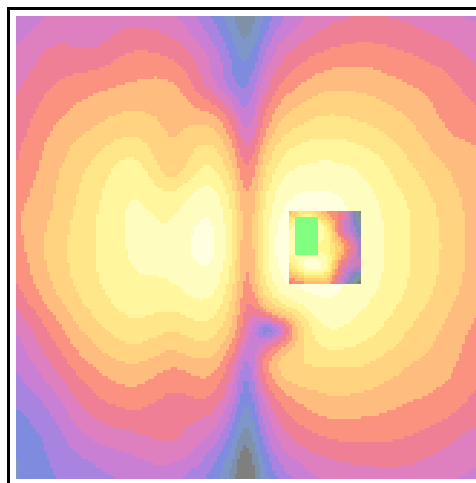Device Reference Point: 0.000, 0.000, -6.30 mm
Cursor:
ABM1/ABM2 = 48.0 dB
ABM1 comp = -9.65 dB A/m
BWC Factor = 0.155979 dB
Location: -6.3, -2, 3.7 mm

0 dB = 260.1

Test Laboratory: COMPTEST/KYOCERA   Date: 04/13/2012

FCC_ C5155_TCoil_CELL_ Closed_Ch.384 y(transversal)
Communication System: CDMA_Tri_BC0&10, Frequency: 836.52 MHz, Duty Cycle: 1:1
Medium: T-Coil,Medium parameters used: σ = 0 mho/m, $ε_r$ = 1; ρ = 0 kg/m^3
Phantom: HAC Test Arch with AMCC,Phantom section: TCoil Section
DASY4 Configuration:
Probe: AM1DV2 - 1045, , Calibrated: 9/15/2011
Sensor-Surface: 0mm (Fix Surface),
Electronics: DAE4 Sn527,Calibrated: 7/13/2011
Measurement SW: DASY4, V4.7 Build 80
Postprocessing SW: SEMCAD, V1.8 Build 186
Temperature:
Room T = 21.8   1 deg C, Liquid T = 22.0   1 deg C

General Scans_384/y (transversal) 4.2mm 50 x 50/ABM Interpolated SNR(x,y,z) (121x121x1):
Measurement grid: dx=10mm, dy=10mm
Signal Type: Audio File (.wav) 48k_voice_1kHz_1s.wav
BWC applied: 0.155979 dB
Device Reference Point: 0.000, 0.000, -6.30 mm
Cursor:
ABM1/ABM2 = 47.8 dB
ABM1 comp = -9.62 dB A/m
BWC Factor = 0.155979 dB
Location: 0.8, 7.5, 3.7 mm

General Scans_384/y (transversal) fine 2mm 8 x 8/ABM Interpolated SNR(x,y,z) (41x41x1):
Measurement grid: dx=10mm, dy=10mm
Signal Type: Audio File (.wav) 48k_voice_1kHz_1s.wav
BWC applied: 0.155979 dB
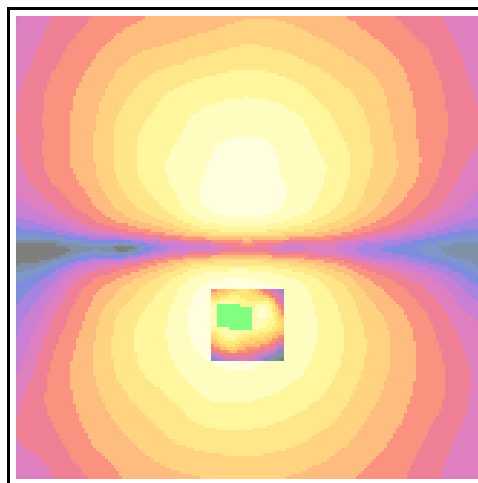Device Reference Point: 0.000, 0.000, -6.30 mm
Cursor:
ABM1/ABM2 = 47.7 dB
ABM1 comp = -9.72 dB A/m
BWC Factor = 0.155979 dB
Location: 2, 7.1, 3.7 mm

0 dB = 246.6

Test Laboratory: COMPTEST/KYOCERA   Date: 04/13/2012

FCC_ C5155_TCoil_CELL_Closed_Ch. 777 z(axial)
Communication System: CDMA_Tri_BC0&10, Frequency: 848.31 MHz, Duty Cycle: 1:1
Medium: T-Coil,Medium parameters used: σ = 0 mho/m, $ε_r$ = 1; ρ = 0 kg/m^3
Phantom: HAC Test Arch with AMCC,Phantom section: TCoil Section
DASY4 Configuration:
Probe: AM1DV2 - 1045, , Calibrated: 9/15/2011
Sensor-Surface: 0mm (Fix Surface),
Electronics: DAE4 Sn527,Calibrated: 7/13/2011
Measurement SW: DASY4, V4.7 Build 80
Postprocessing SW: SEMCAD, V1.8 Build 186
Temperature:
Room T = 21.8   1 deg C, Liquid T = 22.0   1 deg C

General Scans_777/z (axial) 4.2mm 50 x 50/ABM Interpolated SNR(x,y,z) (121x121x1):
Measurement grid: dx=10mm, dy=10mm
Signal Type: Audio File (.wav) 48k_voice_1kHz_1s.wav
BWC applied: 0.155979 dB
Device Reference Point: 0.000, 0.000, -6.30 mm
Cursor:
ABM1/ABM2 = 52.3 dB
ABM1 comp = -1.09 dB A/m
BWC Factor = 0.155979 dB
Location: 0.4, 0, 3.7 mm

General Scans_777/z (axial) fine 2mm 8 x 8/ABM Interpolated SNR(x,y,z) (41x41x1):
Measurement grid: dx=10mm, dy=10mm
Signal Type: Audio File (.wav) 48k_voice_1kHz_1s.wav
BWC applied: 0.155979 dB
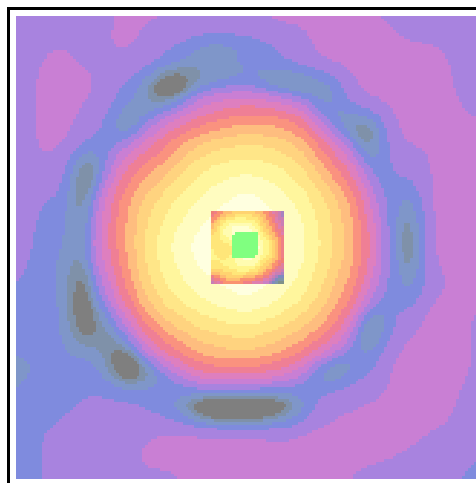Device Reference Point: 0.000, 0.000, -6.30 mm
Cursor:
ABM1/ABM2 = 52.4 dB
ABM1 comp = -0.855 dB A/m
BWC Factor = 0.155979 dB
Location: 0, -0.6, 3.7 mm

0 dB = 412.0

Test Laboratory: COMPTEST/KYOCERA

Date: 6/13/2011

FCC_ C5155_TCoil_CELL_Closed_Ch. 777 x(longitudinal)
Communication System: CDMA_Tri_BC0&10, Frequency: 848.31 MHz, Duty Cycle: 1:1
Medium: T-Coil,Medium parameters used: $\sigma = 0$ mho/m, $\varepsilon_r = 1$; $\rho = 0$ kg/m^3
Phantom: HAC Test Arch with AMCC,Phantom section: TCoil Section
DASY4 Configuration:
Probe: AM1DV2 - 1045, , Calibrated: 9/15/2011
Sensor-Surface: 0mm (Fix Surface),
Electronics: DAE4 Sn527,Calibrated: 7/13/2011
Measurement SW: DASY4, V4.7 Build 80
Postprocessing SW: SEMCAD, V1.8 Build 186
Temperature:
Room T = 21.8   1 deg C, Liquid T = 22.0   1 deg C

General Scans_777/x (longitudinal) 4.2mm 50 x 50/ABM Interpolated SNR(x,y,z) (121x121x1):
Measurement grid: dx=10mm, dy=10mm
Signal Type: Audio File (.wav) 48k_voice_1kHz_1s.wav
BWC applied: 0.155979 dB
Device Reference Point: 0.000, 0.000, -6.30 mm
Cursor:
ABM1/ABM2 = 47.4 dB
ABM1 comp = -10.4 dB A/m
BWC Factor = 0.155979 dB
Location: -7.5, -0.4, 3.7 mm

General Scans_777/x (longitudinal) fine 2mm 8 x 8/ABM Interpolated SNR(x,y,z) (41x41x1):
Measurement grid: dx=10mm, dy=10mm
Signal Type: Audio File (.wav) 48k_voice_1kHz_1s.wav
BWC applied: 0.155979 dB
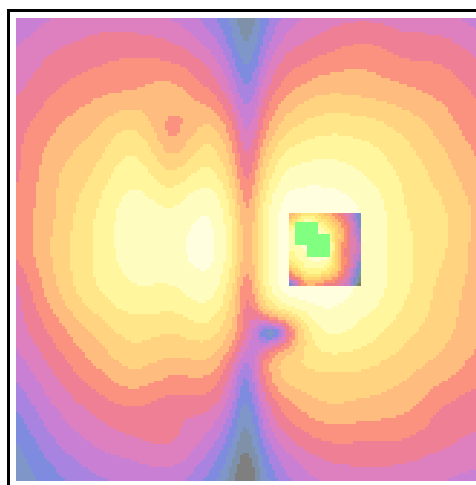Device Reference Point: 0.000, 0.000, -6.30 mm
Cursor:
ABM1/ABM2 = 48.0 dB
ABM1 comp = -9.51 dB A/m
BWC Factor = 0.155979 dB
Location: -6.3, -1.6, 3.7 mm

0 dB = 234.6

Test Laboratory: COMPTEST/KYOCERA   Date: 04/13/2012

FCC_ C5155_TCoil_CELL_Closed_Ch. 777 y(transveral)
Communication System: CDMA_Tri_BC0&10, Frequency: 848.31 MHz, Duty Cycle: 1:1
Medium: T-Coil,Medium parameters used: σ = 0 mho/m, ε_r = 1; ρ = 0 kg/m^3
Phantom: HAC Test Arch with AMCC,Phantom section: TCoil Section
DASY4 Configuration:
Probe: AM1DV2 - 1045, , Calibrated: 9/15/2011
Sensor-Surface: 0mm (Fix Surface),
Electronics: DAE4 Sn527,Calibrated: 7/13/2011
Measurement SW: DASY4, V4.7 Build 80
Postprocessing SW: SEMCAD, V1.8 Build 186
Temperature:
Room T = 21.8   1 deg C, Liquid T = 22.0   1 deg C

General Scans_777/y (transversal) 4.2mm 50 x 50/ABM Interpolated SNR(x,y,z) (121x121x1):
Measurement grid: dx=10mm, dy=10mm
Signal Type: Audio File (.wav) 48k_voice_1kHz_1s.wav
BWC applied: 0.155979 dB
Device Reference Point: 0.000, 0.000, -6.30 mm
Cursor:
ABM1/ABM2 = 47.7 dB
ABM1 comp = -9.66 dB A/m
BWC Factor = 0.155979 dB
Location: 0.4, 7.9, 3.7 mm

General Scans_777/y (transversal) fine 2mm 8 x 8/ABM Interpolated SNR(x,y,z) (41x41x1):
Measurement grid: dx=10mm, dy=10mm
Signal Type: Audio File (.wav) 48k_voice_1kHz_1s.wav
BWC applied: 0.155979 dB
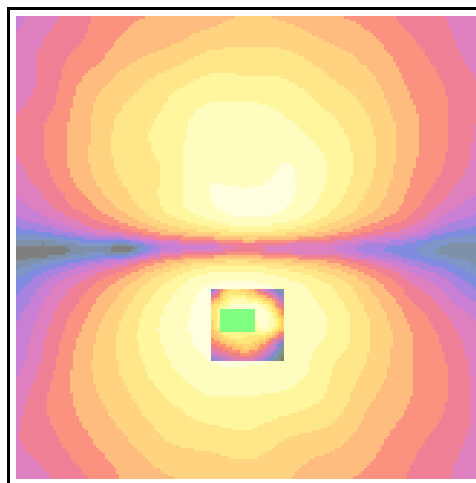Device Reference Point: 0.000, 0.000, -6.30 mm
Cursor:
ABM1/ABM2 = 47.7 dB
ABM1 comp = -9.70 dB A/m
BWC Factor = 0.155979 dB
Location: 1.8, 7.7, 3.7 mm

0 dB = 242.6

PCS

Test Laboratory: COMPTEST/KYOCERA   Date: 04/11/2012

FCC_ C5155_TCoil_PCS_ Closed Ch. 25 z(axial)
Communication System: CDMA-1900, Frequency: 1851.25 MHz, Duty Cycle: 1:1
Medium: T-Coil,Medium parameters used: $\sigma = 0$ mho/m, $\varepsilon_r = 1$; $\rho = 0$ kg/m^3
Phantom: HAC Test Arch with AMCC,Phantom section: TCoil Section
DASY4 Configuration:
Probe: AM1DV2 - 1045, , Calibrated: 9/15/2011
Sensor-Surface: 0mm (Fix Surface),
Electronics: DAE4 Sn527,Calibrated: 7/13/2011
Measurement SW: DASY4, V4.7 Build 80
Postprocessing SW: SEMCAD, V1.8 Build 186
Temperature:
Room T = 21.8 +/- 1 deg C, Liquid T = 22.0 +/- 1 deg C

General Scans_25/z (axial) 4.2mm 50 x 50/ABM Interpolated SNR(x,y,z) (121x121x1):
Measurement grid: dx=10mm, dy=10mm
Signal Type: Audio File (.wav) 48k_voice_1kHz_1s.wav
BWC applied: 0.155979 dB
Device Reference Point: 0.000, 0.000, -6.30 mm
Cursor:
ABM1/ABM2 = 51.9 dB
ABM1 comp = -1.51 dB A/m
BWC Factor = 0.155979 dB
Location: 0.4, 0, 3.7 mm

General Scans_25/z (axial) fine 2mm 8 x 8/ABM Interpolated SNR(x,y,z) (41x41x1):
Measurement grid: dx=10mm, dy=10mm
Signal Type: Audio File (.wav) 48k_voice_1kHz_1s.wav
BWC applied: 0.155979 dB
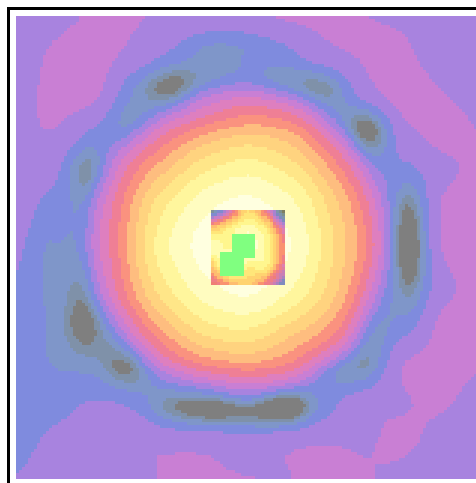Device Reference Point: 0.000, 0.000, -6.30 mm
Cursor:
ABM1/ABM2 = 51.5 dB
ABM1 comp = -1.85 dB A/m
BWC Factor = 0.155979 dB
Location: 1.8, 1.8, 3.7 mm

0 dB = 393.7

Test Laboratory: COMPTEST/KYOCERA   Date: 04/11/2012

FCC_ C5155_TCoil_PCS_Closed_ Ch. 25 x(longitudinal)
Communication System: CDMA-1900, Frequency: 1851.25 MHz, Duty Cycle: 1:1
Medium: T-Coil,Medium parameters used: σ = 0 mho/m, $ε_r$ = 1; ρ = 0 kg/m^3
Phantom: HAC Test Arch with AMCC,Phantom section: TCoil Section
DASY4 Configuration:
Probe: AM1DV2 - 1045, , Calibrated: 9/15/2011
Sensor-Surface: 0mm (Fix Surface),
Electronics: DAE4 Sn527,Calibrated: 7/13/2011
Measurement SW: DASY4, V4.7 Build 80
Postprocessing SW: SEMCAD, V1.8 Build 186
Temperature:
Room T = 21.8 +/- 1 deg C, Liquid T = 22.0 +/- 1 deg C

General Scans_25/x (longitudinal) 4.2mm 50 x 50/ABM Interpolated SNR(x,y,z) (121x121x1):
Measurement grid: dx=10mm, dy=10mm
Signal Type: Audio File (.wav) 48k_voice_1kHz_1s.wav
BWC applied: 0.155979 dB
Device Reference Point: 0.000, 0.000, -6.30 mm
Cursor:
ABM1/ABM2 = 46.2 dB
ABM1 comp = -10.9 dB A/m
BWC Factor = 0.155979 dB
Location: -7.5, -0.4, 3.7 mm

General Scans_25/x (longitudinal) fine 2mm 8 x 8/ABM Interpolated SNR(x,y,z) (41x41x1):
Measurement grid: dx=10mm, dy=10mm
Signal Type: Audio File (.wav) 48k_voice_1kHz_1s.wav
BWC applied: 0.155979 dB
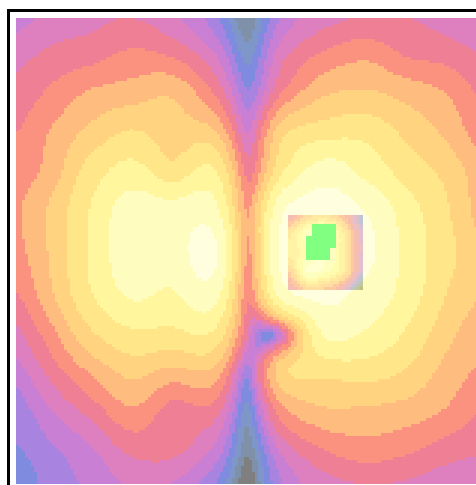Device Reference Point: 0.000, 0.000, -6.30 mm
Cursor:
ABM1/ABM2 = 46.5 dB
ABM1 comp = -10.5 dB A/m
BWC Factor = 0.155979 dB
Location: -7.9, -1.6, 3.7 mm

0 dB = 205.0

Test Laboratory: COMPTEST/KYOCERA   Date: 04/11/2012

FCC_ C5155_TCoil_PCS_Closed_ Ch. 25 y(transversal)
Communication System: CDMA-1900, Frequency: 1851.25 MHz, Duty Cycle: 1:1
Medium: T-Coil,Medium parameters used: $\sigma = 0$ mho/m, $\varepsilon_r = 1$; $\rho = 0$ kg/m^3
Phantom: HAC Test Arch with AMCC,Phantom section: TCoil Section
DASY4 Configuration:
Probe: AM1DV2 - 1045, , Calibrated: 9/15/2011
Sensor-Surface: 0mm (Fix Surface),
Electronics: DAE4 Sn527,Calibrated: 7/13/2011
Measurement SW: DASY4, V4.7 Build 80
Postprocessing SW: SEMCAD, V1.8 Build 186
Temperature:
Room T = 21.8 +/- 1 deg C, Liquid T = 22.0 +/- 1 deg C

General Scans_25/y (transversal) 4.2mm 50 x 50/ABM Interpolated SNR(x,y,z) (121x121x1):
Measurement grid: dx=10mm, dy=10mm
Signal Type: Audio File (.wav) 48k_voice_1kHz_1s.wav
BWC applied: 0.155979 dB
Device Reference Point: 0.000, 0.000, -6.30 mm
Cursor:
ABM1/ABM2 = 46.9 dB
ABM1 comp = -10.8 dB A/m
BWC Factor = 0.155979 dB
Location: 0.4, 8.3, 3.7 mm

General Scans_25/y (transversal) fine 2mm 8 x 8/ABM Interpolated SNR(x,y,z) (41x41x1):
Measurement grid: dx=10mm, dy=10mm
Signal Type: Audio File (.wav) 48k_voice_1kHz_1s.wav
BWC applied: 0.155979 dB
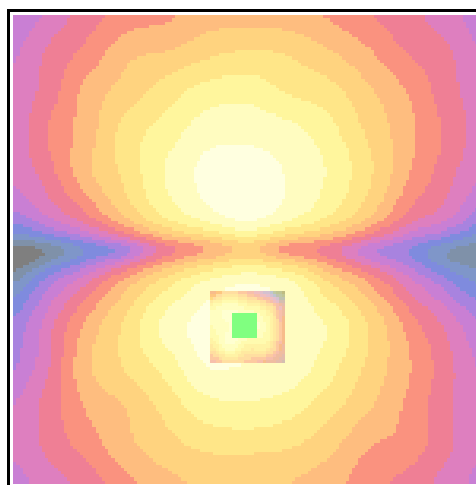Device Reference Point: 0.000, 0.000, -6.30 mm
Cursor:
ABM1/ABM2 = 46.9 dB
ABM1 comp = -10.5 dB A/m
BWC Factor = 0.155979 dB
Location: 0.2, 8.1, 3.7 mm

0 dB = 220.9

Test Laboratory: COMPTEST/KYOCERA   Date: 04/11/2012

FCC_ C5155_TCoil_PCS_Closed_ Ch. 600 z(axial)
Communication System: CDMA-1900, Frequency: 1880 MHz, Duty Cycle: 1:1
Medium: T-Coil,Medium parameters used: σ = 0 mho/m, ε_r = 1; ρ = 0 kg/m^3
Phantom: HAC Test Arch with AMCC,Phantom section: TCoil Section
DASY4 Configuration:
Probe: AM1DV2 - 1045, , Calibrated: 9/15/2011
Sensor-Surface: 0mm (Fix Surface),
Electronics: DAE4 Sn527,Calibrated: 7/13/2011
Measurement SW: DASY4, V4.7 Build 80
Postprocessing SW: SEMCAD, V1.8 Build 186
Temperature:
Room T = 21.8 +/- 1 deg C, Liquid T = 22.0 +/- 1 deg C

General Scans_600/z (axial) 4.2mm 50 x 50/ABM Interpolated SNR(x,y,z) (121x121x1):
Measurement grid: dx=10mm, dy=10mm
Signal Type: Audio File (.wav) 48k_voice_1kHz_1s.wav
BWC applied: 0.155979 dB
Device Reference Point: 0.000, 0.000, -6.30 mm
Cursor:
ABM1/ABM2 = 52.6 dB
ABM1 comp = -1.19 dB A/m
BWC Factor = 0.155979 dB
Location: 0.4, 0, 3.7 mm

General Scans_600/z (axial) fine 2mm 8 x 8/ABM Interpolated SNR(x,y,z) (41x41x1):
Measurement grid: dx=10mm, dy=10mm
Signal Type: Audio File (.wav) 48k_voice_1kHz_1s.wav
BWC applied: 0.155979 dB
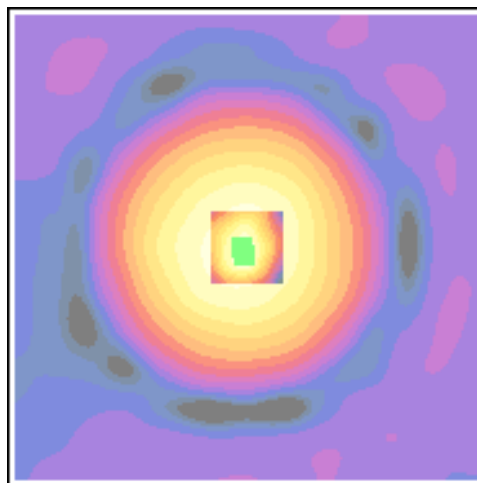Device Reference Point: 0.000, 0.000, -6.30 mm
Cursor:
ABM1/ABM2 = 51.9 dB
ABM1 comp = -1.65 dB A/m
BWC Factor = 0.155979 dB
Location: 0.4, 0.8, 3.7 mm

0 dB = 424.3

Test Laboratory: COMPTEST/KYOCERA   Date: 04/11/2012

FCC_ C5155_TCoil_PCS _Closed_Ch. 600 x(longitudinal)
Communication System: CDMA-1900, Frequency: 1880 MHz, Duty Cycle: 1:1
Medium: T-Coil,Medium parameters used: σ = 0 mho/m, $ε_r$ = 1; ρ = 0 kg/m^3
Phantom: HAC Test Arch with AMCC,Phantom section: TCoil Section
DASY4 Configuration:
Probe: AM1DV2 - 1045, , Calibrated: 9/15/2011
Sensor-Surface: 0mm (Fix Surface),
Electronics: DAE4 Sn527,Calibrated: 7/13/2011
Measurement SW: DASY4, V4.7 Build 80
Postprocessing SW: SEMCAD, V1.8 Build 186
Temperature:
Room T = 21.8 +/- 1 deg C, Liquid T = 22.0 +/- 1 deg C

General Scans_600/x (longitudinal) 4.2mm 50 x 50/ABM Interpolated SNR(x,y,z) (121x121x1):
Measurement grid: dx=10mm, dy=10mm
Signal Type: Audio File (.wav) 48k_voice_1kHz_1s.wav
BWC applied: 0.155979 dB
Device Reference Point: 0.000, 0.000, -6.30 mm
Cursor:
ABM1/ABM2 = 46.6 dB
ABM1 comp = -10.5 dB A/m
BWC Factor = 0.155979 dB
Location: -6.2, 0, 3.7 mm

General Scans_600/x (longitudinal) fine 2mm 8 x 8/ABM Interpolated SNR(x,y,z) (41x41x1):
Measurement grid: dx=10mm, dy=10mm
Signal Type: Audio File (.wav) 48k_voice_1kHz_1s.wav
BWC applied: 0.155979 dB
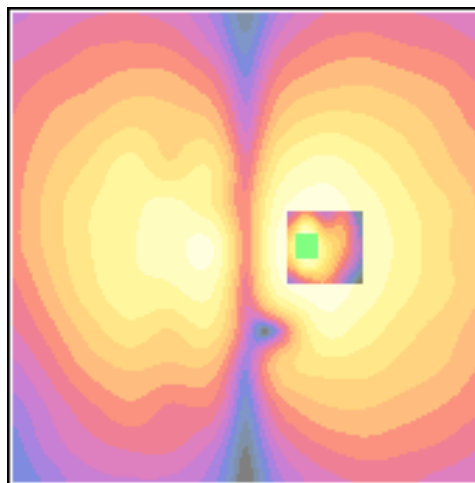Device Reference Point: 0.000, 0.000, -6.30 mm
Cursor:
ABM1/ABM2 = 46.8 dB
ABM1 comp = -10.2 dB A/m
BWC Factor = 0.155979 dB
Location: -6.3, -0.4, 3.7 mm

0 dB = 214.3

Test Laboratory: COMPTEST/KYOCERA   Date: 04/11/2012

FCC_ C5155_TCoil_PCS_Closed_ Ch. 600 y(transversal)
Communication System: CDMA-1900, Frequency: 1880 MHz, Duty Cycle: 1:1
Medium: T-Coil,Medium parameters used: $\sigma = 0$ mho/m, $\varepsilon_r = 1$; $\rho = 0$ kg/m^3
Phantom: HAC Test Arch with AMCC,Phantom section: TCoil Section
DASY4 Configuration:
Probe: AM1DV2 - 1045, , Calibrated: 9/15/2011
Sensor-Surface: 0mm (Fix Surface),
Electronics: DAE4 Sn527,Calibrated: 7/13/2011
Measurement SW: DASY4, V4.7 Build 80
Postprocessing SW: SEMCAD, V1.8 Build 186
Temperature:
Room T = 21.8 +/- 1 deg C, Liquid T = 22.0 +/- 1 deg C

General Scans_600/y (transversal) 4.2mm 50 x 50/ABM Interpolated SNR(x,y,z) (121x121x1):
Measurement grid: dx=10mm, dy=10mm
Signal Type: Audio File (.wav) 48k_voice_1kHz_1s.wav
BWC applied: 0.155979 dB
Device Reference Point: 0.000, 0.000, -6.30 mm
Cursor:
ABM1/ABM2 = 47.0 dB
ABM1 comp = -10.5 dB A/m
BWC Factor = 0.155979 dB
Location: 0.8, 8.3, 3.7 mm

General Scans_600/y (transversal) fine 2mm 8 x 8/ABM Interpolated SNR(x,y,z) (41x41x1):
Measurement grid: dx=10mm, dy=10mm
Signal Type: Audio File (.wav) 48k_voice_1kHz_1s.wav
BWC applied: 0.155979 dB
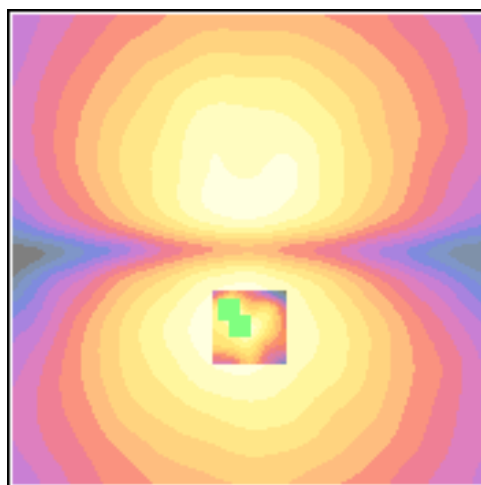Device Reference Point: 0.000, 0.000, -6.30 mm
Cursor:
ABM1/ABM2 = 47.0 dB
ABM1 comp = -10.1 dB A/m
BWC Factor = 0.155979 dB
Location: 2, 6.5, 3.7 mm

0 dB = 223.1

Test Laboratory: COMPTEST/KYOCERA

Date: 04/11/2012

FCC_ C5155_TCoil_PCS_Closed_Ch. 1175 z(axial)
Communication System: CDMA-1900, Frequency: 1908.75 MHz, Duty Cycle: 1:1
Medium: T-Coil,Medium parameters used: $\sigma = 0$ mho/m, $\varepsilon_r = 1$; $\rho = 0$ kg/m^3
Phantom: HAC Test Arch with AMCC,Phantom section: TCoil Section
DASY4 Configuration:
Probe: AM1DV2 - 1045, , Calibrated: 9/15/2011
Sensor-Surface: 0mm (Fix Surface),
Electronics: DAE4 Sn527,Calibrated: 7/13/2011
Measurement SW: DASY4, V4.7 Build 80
Postprocessing SW: SEMCAD, V1.8 Build 186
Temperature:
Room T = 21.8 +/- 1 deg C, Liquid T = 22.0 +/- 1 deg C

General Scans_1175/z (axial) 4.2mm 50 x 50/ABM Interpolated SNR(x,y,z) (121x121x1):
Measurement grid: dx=10mm, dy=10mm
Signal Type: Audio File (.wav) 48k_voice_1kHz_1s.wav
BWC applied: 0.155979 dB
Device Reference Point: 0.000, 0.000, -6.30 mm
Cursor:
ABM1/ABM2 = 52.2 dB
ABM1 comp = -0.947 dB A/m
BWC Factor = 0.155979 dB
Location: 0, 0, 3.7 mm

General Scans_1175/z (axial) fine 2mm 8 x 8/ABM Interpolated SNR(x,y,z) (41x41x1):
Measurement grid: dx=10mm, dy=10mm
Signal Type: Audio File (.wav) 48k_voice_1kHz_1s.wav
BWC applied: 0.155979 dB
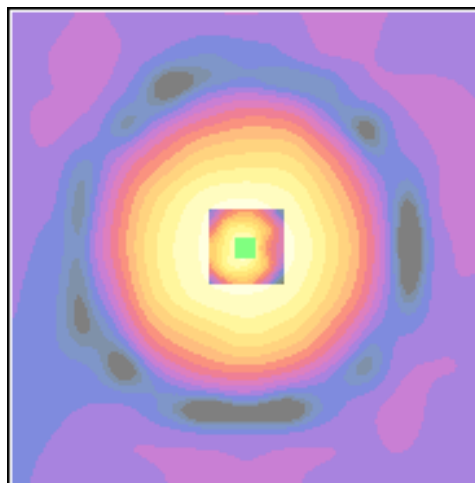Device Reference Point: 0.000, 0.000, -6.30 mm
Cursor:
ABM1/ABM2 = 52.4 dB
ABM1 comp = -0.748 dB A/m
BWC Factor = 0.155979 dB
Location: 0.2, 0, 3.7 mm

0 dB = 406.7

Test Laboratory: COMPTEST/KYOCERA   Date: 04/11/2012

FCC_ C5155_TCoil_PCS_Closed_ Ch. 1175 x(longitudinal)
Communication System: CDMA-1900, Frequency: 1908.75 MHz, Duty Cycle: 1:1
Medium: T-Coil,Medium parameters used: $\sigma = 0$ mho/m, $\varepsilon_r = 1$; $\rho = 0$ kg/m^3
Phantom: HAC Test Arch with AMCC,Phantom section: TCoil Section
DASY4 Configuration:
Probe: AM1DV2 - 1045, , Calibrated: 9/15/2011
Sensor-Surface: 0mm (Fix Surface),
Electronics: DAE4 Sn527,Calibrated: 7/13/2011
Measurement SW: DASY4, V4.7 Build 80
Postprocessing SW: SEMCAD, V1.8 Build 186
Temperature:
Room T = 21.8 +/- 1 deg C, Liquid T = 22.0 +/- 1 deg C

General Scans_1175/x (longitudinal) 4.2mm 50 x 50/ABM Interpolated SNR(x,y,z) (121x121x1):
Measurement grid: dx=10mm, dy=10mm
Signal Type: Audio File (.wav) 48k_voice_1kHz_1s.wav
BWC applied: 0.155979 dB
Device Reference Point: 0.000, 0.000, -6.30 mm
Cursor:
ABM1/ABM2 = 46.8 dB
ABM1 comp = -10.8 dB A/m
BWC Factor = 0.155979 dB
Location: -7.5, 0.4, 3.7 mm

General Scans_1175/x (longitudinal) fine 2mm 8 x 8/ABM Interpolated SNR(x,y,z) (41x41x1):
Measurement grid: dx=10mm, dy=10mm
Signal Type: Audio File (.wav) 48k_voice_1kHz_1s.wav
BWC applied: 0.155979 dB
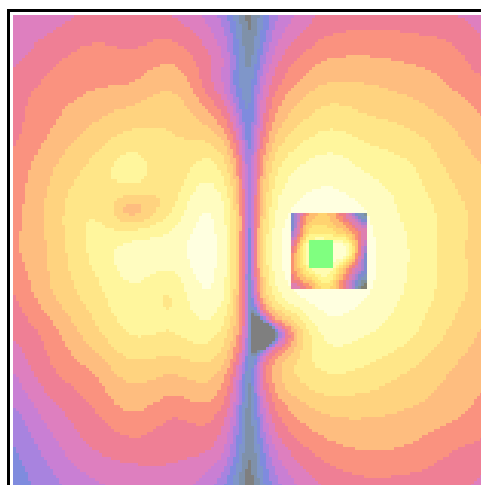Device Reference Point: 0.000, 0.000, -6.30 mm
Cursor:
ABM1/ABM2 = 47.1 dB
ABM1 comp = -10.5 dB A/m
BWC Factor = 0.155979 dB
Location: -7.5, 0.2, 3.7 mm

0 dB = 217.8

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Test Laboratory: COMPTEST/KYOCERA   Date: 04/11/2012

FCC_ C5155_TCoil_PCS_Closed_ Ch. 1175 y(transversal)
Communication System: CDMA-1900, Frequency: 1908.75 MHz, Duty Cycle: 1:1
Medium: T-Coil,Medium parameters used: σ = 0 mho/m, $ε_r$ = 1; ρ = 0 kg/m^3
Phantom: HAC Test Arch with AMCC,Phantom section: TCoil Section
DASY4 Configuration:
Probe: AM1DV2 - 1045, , Calibrated: 9/15/2011
Sensor-Surface: 0mm (Fix Surface),
Electronics: DAE4 Sn527,Calibrated: 7/13/2011
Measurement SW: DASY4, V4.7 Build 80
Postprocessing SW: SEMCAD, V1.8 Build 186
Temperature:
Room T = 21.8 +/- 1 deg C, Liquid T = 22.0 +/- 1 deg C

General Scans_1175/y (transversal) 4.2mm 50 x 50/ABM Interpolated SNR(x,y,z) (121x121x1):
Measurement grid: dx=10mm, dy=10mm
Signal Type: Audio File (.wav) 48k_voice_1kHz_1s.wav
BWC applied: 0.155979 dB
Device Reference Point: 0.000, 0.000, -6.30 mm
Cursor:
ABM1/ABM2 = 47.2 dB
ABM1 comp = -10.3 dB A/m
BWC Factor = 0.155979 dB
Location: 0.8, 8.7, 3.7 mm

General Scans_1175/y (transversal) fine 2mm 8 x 8/ABM Interpolated SNR(x,y,z) (41x41x1):
Measurement grid: dx=10mm, dy=10mm
Signal Type: Audio File (.wav) 48k_voice_1kHz_1s.wav
BWC applied: 0.155979 dB
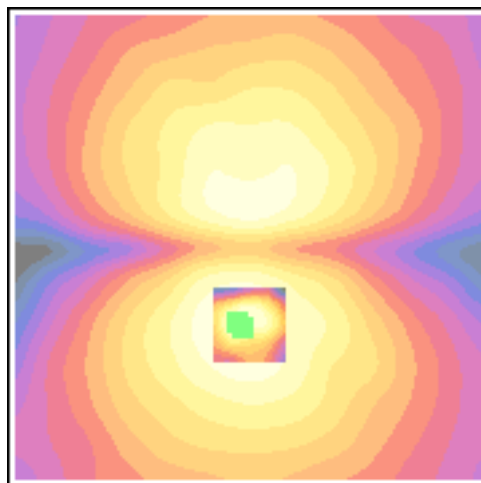Device Reference Point: 0.000, 0.000, -6.30 mm
Cursor:
ABM1/ABM2 = 47.2 dB
ABM1 comp = -10.2 dB A/m
BWC Factor = 0.155979 dB
Location: 1.4, 7.9, 3.7 mm

0 dB = 228.6